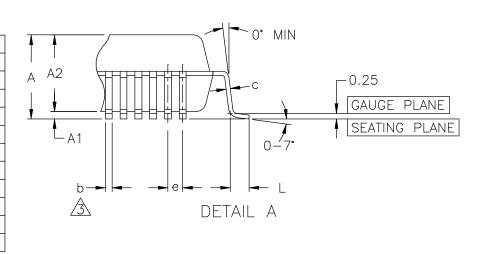


NOTES:

- 1. DIMENSIONS D1 AND E1 INCLUDE MOLD MISMATCH, BUT DO NOT INCLUDE MOLD PROTRUSION.
- DETAILS OF PIN 1 IDENTIFIER ARE OPTIONAL BUT MUST BE LOCATED WITHIN THE ZONE INDICATED.
- 3 DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. PROTRUSION NOT TO BE LOCATED ON LOWER RADIUS OR FOOT OF LEAD.
 - 4. ALL DIMENSIONS ARE IN MILLIMETERS.

DIM	MIN	MAX			
Α	l	4.07			
A1	0.05	_			
A2	3.17	3.67			
b	0.20	0.40			
С	0.13	0.23			
D	30.35	31.45			
D1	28.00	BSC			
Е	30.35	31.45			
E1	28.00	BSC			
е	0.65	BSC			
L	0.40	1.03			



SIGNATURE	DATE	Dallas Semiconductor								
DOC. CONTROL:			47	Sei	micon	duc	to	r		
ENGR. MGR:		MARKETING OUTLINE, 160 LD. MQFP								
MFG. ENGR:		28X28 MM BODY								
CHECKED BY:		SIZE	FSCM NO	PART	NO.					REV
DRAWN BY:		Α								В
DO NOT SCALE DW	/G.	SCALE	N/A				SHEET	1	OF	1